

ALIGNMENT TOOLS FOR HOLDING ELECTRONIC COMPONENTS PICK & PLACE UNIT OF BUMPS DATASHEET ISP15A787FPI0010

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This workstation allows you to capture and precisely deposit copper balls (bumps) on printed circuits.



Non contractual Photo

1 - Design

Thanks to Venturi directly linked to the compressed air network, the device can place 250 bumps of diameter between Ø1 and Ø1, 6mm.

Then, the bumps are placed on the printed circuits which are first coated with a soldering or sintering paste.

Positioning vane for components ensure a repeatability of the bumps drop on the tracks with an accuracy of ± 0.02 mm.

This vane can be soldered at +250°C to ensure the bumps soldering or sintering on the components.

2 - Applications

- · Prehension by suction and place of the bumps
- Accurate positioning of objects of small size

3 - Technical Specifications

CHARACTERISTICS (off options)	VALUES
Bumps dimensions	Ø1 to Ø1, 6 mm
PCB dimensions	50 x 40 x 1mm
Accuracy of positionning	± 0,02mm
Device dimensions	350 x 300 x 460 mm
Device mass	≤ 8 kg

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4 - Options

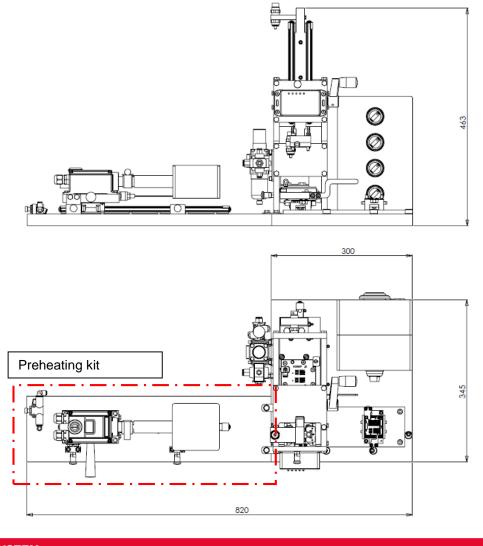
Preheating kit:

- Removable 2KW air heater on guide rail
- Diffusion chamber
- Temperature sensor
- Programmable temperature control

Additional grid for bumps repartition:

- Bumps repartition on the prehension grid , on request
- Same on the grid layout of the bumps

5 - Dimensions



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